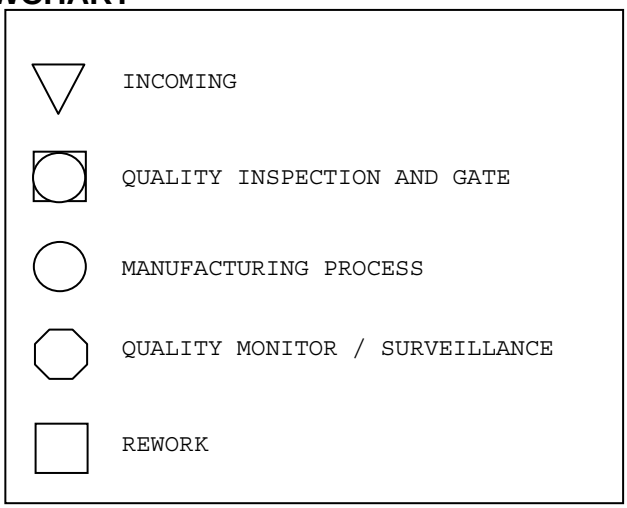
WAFER FABRICATION FLOWCHART

(Updated 1/6/2014)



Vendor:	Linear Technology Corporation
Package:	0.35µm BCD Process
Assembly:	All package Types
Location of Wafer Fab:	Linear Technology Corp., Milpitas & CA.
Assembly:	Linear Technology Corporation, Penang, Malaysia or Approved assembly subcontractor
Final Test:	Linear Technology Corp., Milpitas, CA., Singapore
Q.C. Test:	Linear Technology Corp., Milpitas, CA., Singapore
Source Accept Test:	Linear Technology Corp., Milpitas, CA., Singapore
Quality Contact:	Naib Girn, LTC Milpitas, CA (408) 432-1900 Ext. 2519

FLOW CHART	PROCESS STEP	DESCRIPTION	INSPECTION/TEST CRITERIA	METHOD & EQUIPMENT	SAMPLING PLAN	SPC TECHNIQUE
	INCOMING RAW MATERIAL INSPECTION	WAFERS	VISUAL: SCRATCHES, PITS, HAZE, CRATERS, DIMPLES, CONTAMINATION	1 X INSPECTION	1.0% AQL TO 2.5 AQL LEVEL 1	LOGBOOK
			OXYGEN/CARBON MEASUREMENT	INFRARED SPECTROMETER	S/S=2, ACC = 0	
			RESISTIVITY / CONDUCTIVITY	MAGNETRON V/I METER	S/S=2, ACC = 0	
			DIMENSIONAL	CALIPERS	2.5% AQL, LEVEL 1	
			THICKNESS AND TAPER/BOW	DIAL THICKNESS GAGE	2.5% AQL, LEVEL 1	
			ORIENTATION	BREAK TEST	S/S=1. ACC = 0	
			C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS		EACH BATCH	
		RETICLE	C OF C VERIFICATION		EACH PLATE	
		CHEMICALS	C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS			
		GASES	C OF C VERIFICATION AGAINST "MPS" REQUIREMENTS			
		TARGETS	C OF C VERIFICATION			
	INITIAL OXIDATION	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS / CYCLE	TREND CHART
	N-BURIED LAYER MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	N-BURIED LAYER IMPLANT	IMPLANT	DOSE CHECK	THEMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	N-BURIED LAYER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	P-BURIED LAYER MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	P-BURIED LAYER IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P-BURIED LAYER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
			OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	

EPI	DEPOSIT EPI ASM	VISUAL	UV LAMP	INSPECT 2 WAFERS / RUN	
			INTERFERENCE CONTRAST MICROSCOPE		
		Rs	4 POINT PROBE	2 READING/PASS	X Bar & MOVING R
		EPI THICKNESS	FTIR	1 WAFER/LOT	LOGBOOK
PAD OXIDATION	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
		OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	TREND CHART
HV N-WELL MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
HV N-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
HV P-WELL MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
HV P-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
P+ ISOLATION MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
P+ ISOLATION IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
N+ SINKER MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
N+ SINKER IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	LOGBOOK
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
N-WELL MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
LV N-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
P-WELL MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
LV P-WELL IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
NITRIDE DEPOSITION	LPCVD NITRIDE DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	TREND CHART
			10X MICROSCOPE	2 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
		NITRIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
WELL/SINKER DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
ACTIVE MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
LOCOS OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK TREND CHART
		OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
STRIP NITRIDE	H3PO4 ETCH BATH	VISUAL	UV LAMP MICROSCOPE INSPECTION		LOGBOOK
		THICKNESS	NANOSPEC	2 WAFERS /LOT	
SACRIFICIAL OXIDATION	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
		OXIDE THICKNESS	NANOSPEC	3 WAFERS / CYCLE	TREND CHART
P FIELD IMPLANT MASK	RESIST MASK	VISUAL INSPECTION	MICROSCOPE 400X	"S" PATTERN SCAN OF THE WAFERS	PRODUCTION LOG
BORON FIELD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS / LOT	TREND CHART

STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
PMOS VT IMPLANT MASK	RESIST MASK	VISUAL INSPECTION	MICROSCOPE 400X	"S" PATTERN SCAN OF THE WAFERS	PRODUCTION LOG
PMOS VT IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS / LOT	TREND CHART
PMOS ANTI PUNCH THROUGH IMPLANT	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
STRIP OXIDE	HF ETCH BATH	VISUAL	UV LAMP MICROSCOPE INSPECTION		LOGBOOK
		THICKNESS	NANOSPEC	2 WAFERS /LOT	
THICK GATE OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
		OXIDE THICKNESS	NANOSPEC	3 WAFERS/CYCLE	TREND CHART
VT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
LV THRESHOLD ADJUST IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
VTHV IMPLANT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
HV THRESHOLD ADJUST IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

NPN BASE MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
NPN BASE IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
THIN OXIDE MASK	RESIST MASK/ HF ETCH BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
THIN GATE OXIDE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
		OXIDE THICKNESS	ELLIPSOMETER	3 WAFERS/CYCLE	TREND CHART
POLY 1 DEPOSITION	POLY Si CVD DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	
			10X MICROSCOPE	3 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
		POLY THICKNESS	NANOSPEC	3 WAFERS/CYCLE	TREND CHART
	WSix CVD DEPOSITION	REFLECTIVITY	NANOSPEC	1 WF PER BATCH LOT	
			10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
		Rs	Four Point Probe	1 WF PER BATCH LOT	TREND CHART
CAP OXIDE DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK X-BAR & R
		THICKNESS	ELLIPSOMETER	3 WAFERS/CYCLE	
POLY 2 DEPOSITION	LPCVD DEPOSITION	VISUAL	UV LAMP	100%, MORE THAN 2 COLOR CHANGE IS FAIL	TREND CHART
			10X MICROSCOPE	2 WAFERS/CYCLE <5 DEFECTS/PER FIELD OF VIEW	
		THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
POLY 2 MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
POLY 1 MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
		CRITICAL DIMENSION	SEM	1 WAFER (5 SPOTS)	X BAR & R
PCHAN IMPLANT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
PCHAN IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

	CHANNEL DRIVE	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	NLDD MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	NLDD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	PLDD MASK	RESIST MASK	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	PLDD IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	SPACER DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	SPACER ETCH	PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
			OXIDE MEASUREMENT	NANOSPEC	2 WAFER (3 SPOTS)	X BAR & R
	N+ S/D IMPLANT MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	N+ S/D IMPLANT	IMPLANT	DOSE CHECK	THERMAWAVE	2 WAFERS/LOT	TREND CHART
			VISUAL	MICROSCOPE	2 WAFERS/LOT	
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	P+ S/D MASK	RESIST MASK	DEVELOP INSPECT	UV and MICROSCOPE	5 WAFERS 5 SPOTS AT 100X	PRODUCTION LOG
	P+ S/D IMPLANT	IMPLANT	DOSE CHECK	THERMAWAFE	2 WAFERS/LOT	TREND CHART
			VISUAL	MICROSCOPE	2 WAFERS/LOT	
	STRIP RESIST	RF PLASMA SULFURIC ACID	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG

	THIN OX DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	S/D ANNEAL	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	RTA ANNEAL	RTA	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	PRE-METAL HDP PSG DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
			WT% P	BIORAD	WEEKLY	
	PRE-METAL USG DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	3 WAFERS/CYCLE	
	PRE-METAL OXIDE CMP	OXIDE POLISH	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	OPTI-PROBE	3 WAFERS/CYCLE	
			PROFILE	PROFILOMETER	3 WAFERS/CYCLE	
	THIN FILM DEPOSITION	PVD SPUTTER	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	THIN FILM RESISTOR MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 500X	PRODUCTION LOG
			VISUAL INSPECTION	MICROSCOPE 100X	"S" PATTERN SCAN OF THE WAFERS	
	SI-RICH OXIDE	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	CONTACT MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	CONTACT TIN BARRIER	PVD SPUTTER	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	

	CONTACT W PLUG DEPOSITION	CVD	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	CONTACT W PLUG CMP	TUNGSTEN POLISH	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	OPTI-PROBE	3 WAFERS/CYCLE	
			PROFILE	PROFILOMETER	3 WAFERS/CYCLE	
	THIN FILM CONTACT MASK	RESIST MASK HF ETCHANT BATH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X	PRODUCTION LOG
	METAL-1 DEPOSITION	PVD SPUTTER	VISUAL	UV LAMP	2 WAFERS/RUN	LOGBOOK
			VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	TREND CHART
	MIM CAP OXIDE DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	MIM CAP TOP PLATE DEPOSITION DEPOSITION	PVD SPUTTER	VISUAL	UV LAMP	2 WAFERS/RUN	LOGBOOK
			VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	TREND CHART
	MIM CAP TOP PLATE MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	METAL MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	HDP USG DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	TREND CHART
			STRESS	STRESS GAGE	1 WAFER/CYCLE	
	PECVD USG DEPOSITION	OXIDE DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
	INTER-METAL OXIDE CMP	OXIDE POLISH	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	OPTI-PROBE	3 WAFERS/CYCLE	
			PROFILE	PROFILOMETER	3 WAFERS/CYCLE	
	VIA MASK	RESIST MASK PLASMA ETCH	FINAL INSPECT	UV and MICROSCOPE	5 WAFERS "S" PATTERN SCAN AT 200X AND 1000X	PRODUCTION LOG
	VIA TIN BARRIER	PVD SPUTTER	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	VIA W PLUG DEPOSITION	CVD	VISUAL	10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	TREND CHART
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	VIA W PLUG CMP	TUNGSTEN POLISH	VISUAL	UV LAMP	3 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	OPTI-PROBE	3 WAFERS/CYCLE	
			PROFILE	PROFILOMETER	3 WAFERS/CYCLE	
	METAL-2 DEPOSITION	PVD SPUTTER	VISUAL	UV LAMP	2 WAFERS/RUN	LOGBOOK
				10X MICROSCOPE	2 WAFERS/RUN <5 DEFECTS PER FIELD OF VIEW	
			Rs	FOUR POINT PROBE	1 WAFERS/LOT	
	METAL MASK	*RESIST MASK* *PLASMA ETCH*	*FINAL INSPECT*	*UV and MICROSCOPE*	*5 WAFERS* *"S" PATTERN SCAN AT 200X AND 1000X*	*PRODUCTION LOG*
	PASSIVATION DEPOSITION	OXIDE / PEN DEPOSITION	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN	LOGBOOK TREND CHART
			THICKNESS	NANOSPEC	1 WAFER/CYCLE	
			INDEX OF REFRACTION	ELLIPSOMETER	1 WAFER/WEEK	
	PAD MASK	*RESIST MASK* *PLASMA ETCH*	*FINAL INSPECT*	*UV and MICROSCOPE*	*5 WAFERS* *"S" PATTERN SCAN AT 200X*	*PRODUCTION LOG*
	ALLOY	FURNACE	VISUAL	UV LAMP MICROSCOPE INSPECTION	2 WAFERS/RUN < 25 DEFECTS PER WAFER	LOGBOOK
	ELECTRICAL TEST	EVALUATE ELECTRICAL PARAMETERS			100%	LOGBOOK